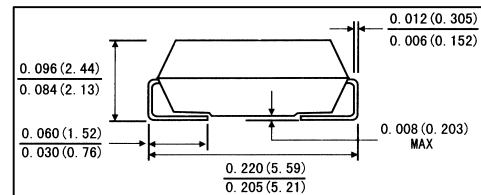
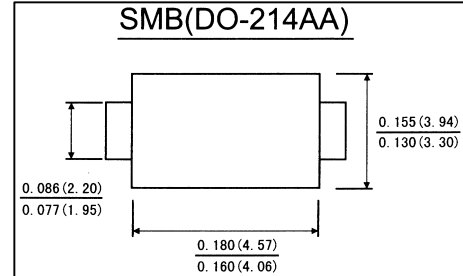


FEATURES

- . For surface mounted applications
- . Glass passivated junction
- . Low profile package
- . Built-in strain relief , ideal for automated placement
- . Plastic package has Underwrites Laboratory Flammability Classification 94V-0
- . High temperature soldering guaranteed: 250°C/10 seconds, at terminals

MECHANICAL DATA

- . **Case:** JEDEC SMA(DO-214AA) molded plastic
- . **Terminals:** Plated axial leads solderable per MIL-STD-750,method 2026
- . **Polarity:** Color band denotes cathode end
- . **Mounting Position:** Any
- . **Weight:** 0.003 ounce, 0.093 gram



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(Ratings at 25°C ambient temperature unless otherwise specified,Single phase, half wave 60Hz, resistive or inductive)

load. For capacitive load, derate current by 20%)

| | Symbols | S2A | S2B | S2D | S2G | S2J | S2K | S2M | Units |
|--|-------------------|-------------------------|-----|-----|-----|-----|-----|------|--------------------|
| Maximum Recurrent peak reverse voltage | V_{RRM} | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | Volts |
| Maximum RMS voltage | V_{RMS} | 35 | 70 | 140 | 280 | 420 | 560 | 700 | Volts |
| Maximum DC blocking voltage | V_{DC} | 50 | 100 | 200 | 400 | 600 | 800 | 100 | Volts |
| Maximum average forward rectified current at $T_L=100^\circ\text{C}$ | $I_{(AV)}$ | 1.5 | | | | | | | Amp |
| Peak forward surge current (8.3ms half sine wave superimposed on rated load (JEDEC method) $T_L=100^\circ\text{C}$ | I_{FSM} | 50.0 | | | | | | | Amps |
| Maximum instantaneous forward voltage at 1.0 A | V_F | 1.15 | | | | | | | Volts |
| Maximum reverse recovery time(Note 1) current at rated DC Blocking Voltage | I_R | $T_A=25^\circ\text{C}$ | | | | | | | μA |
| | | $T_A=125^\circ\text{C}$ | | | | | | | |
| Typical Thermal Resistance(Note 2) | $R_{\theta_{JL}}$ | 16.0 | | | | | | | $^\circ\text{C/W}$ |
| | $R_{\theta_{JA}}$ | 53.0 | | | | | | | |
| Typical reverse recovery time(Note 3) | T_{rr} | 2.0 | | | | | | | μS |
| Typical junction capacitance(Note 1) | | 30.0 | | | | | | | pF |
| Operating and storage temperature range | $T_J T_{STG}$ | -55 to +150 | | | | | | | $^\circ\text{C}$ |

Notes: 1.Measured at 1MHz and applied reverse voltage of 4.0V DC.

2.Thermal resistance from junction to ambient and from junction to lead mounted on 0.2 X 0.2"(5.0 X 5.0mm)

copper pad areas. 3.Reverse recovery test conditions: $I_F=0.5A, I_R=1.0A, I_{rr}=0.25A$.

RATINGS AND CHARACTERISTIC CURVES S2A THRU S2M

FIG.1-FORWARD CURRENT DERATING CURVE

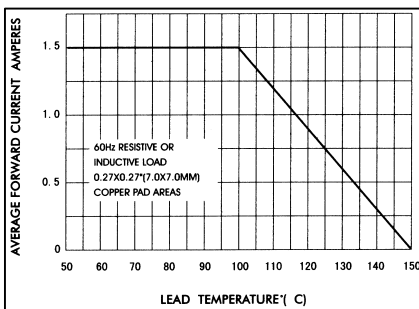


FIG.2-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

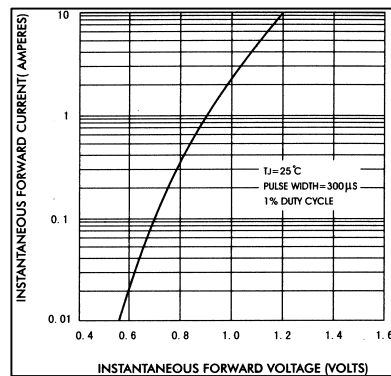


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

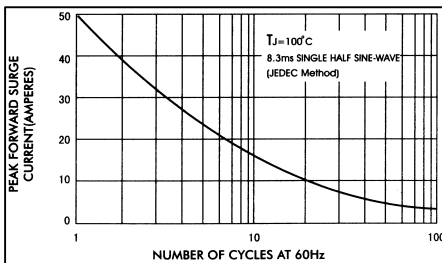


FIG.4-TYPICAL REVERSE CHARACTERISTICS

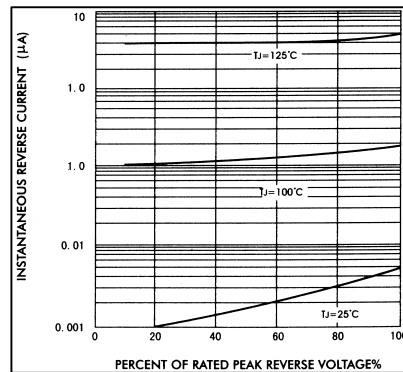


FIG.5-TYPICAL JUNCTION CAPACITANCE

